

## High Speed CMOS Logic 8-Bit Universal Shift Register; Three-State

January 1998

### Features

- Buffered Inputs
- Four Operating Modes: Shift Left, Shift Right, Load and Store
- Can be Cascaded for N-Bit Word Lengths
- I/O<sub>0</sub> - I/O<sub>7</sub> Bus Drive Capability and Three-State for Bus Oriented Applications
- Typical f<sub>MAX</sub> = 50MHz at V<sub>CC</sub> = 5V, C<sub>L</sub> = 15pF, T<sub>A</sub> = 25°C
- Fanout (Over Temperature Range)
  - Standard Outputs . . . . . 10 LSTTL Loads
  - Bus Driver Outputs . . . . . 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity: N<sub>IL</sub> = 30%, N<sub>IH</sub> = 30% of V<sub>CC</sub> at V<sub>CC</sub> = 5V
- HCT Types
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility, V<sub>IL</sub> = 0.8V (Max), V<sub>IH</sub> = 2V (Min)
  - CMOS Input Compatibility, I<sub>I</sub> ≤ 1μA at V<sub>OL</sub>, V<sub>OH</sub>

### Description

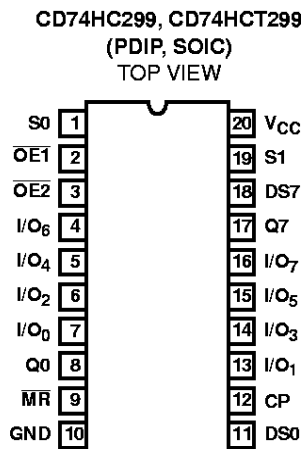
The Harris CD74HC299 and CD74HCT299 are 8-bit shift/storage registers with three-state bus interface capability. The register has four synchronous-operating modes controlled by the two select inputs as shown in the mode select (S0, S1) table. The mode select, the serial data (DS0, DS7) and the parallel data (I/O<sub>0</sub> - I/O<sub>7</sub>) respond only to the low-to-high transition of the clock (CP) pulse. S0, S1 and data inputs must be one set-up time prior to the clock positive transition.

The Master Reset ( $\overline{MR}$ ) is an asynchronous active low input. When  $\overline{MR}$  output is low, the register is cleared regardless of the status of all other inputs. The register can be expanded by cascading same units by tying the serial output (Q0) to the serial data (DS7) input of the preceding register, and tying the serial output (Q7) to the serial data (DS0) input of the following register. Recirculating the (n x 8) bits is accomplished by tying the Q7 of the last stage to the DS0 of the first stage.

The three-state input/output I/O port has three modes of operation:

1. Both output enable ( $\overline{OE1}$  and  $\overline{OE2}$ ) inputs are low and S0 or S1 or both are low, the data in the register is presented at the eight outputs.
2. When both S0 and S1 are high, I/O terminals are in the high impedance state but being input ports, ready for parallel data to be loaded into eight registers with one clock transition regardless of the status of  $\overline{OE1}$  and  $\overline{OE2}$ .
3. Either one of the two output enable inputs being high will force I/O terminals to be in the off-state. It is noted that each I/O terminal is a three-state output and a CMOS buffer input.

### Pinout



### Ordering Information

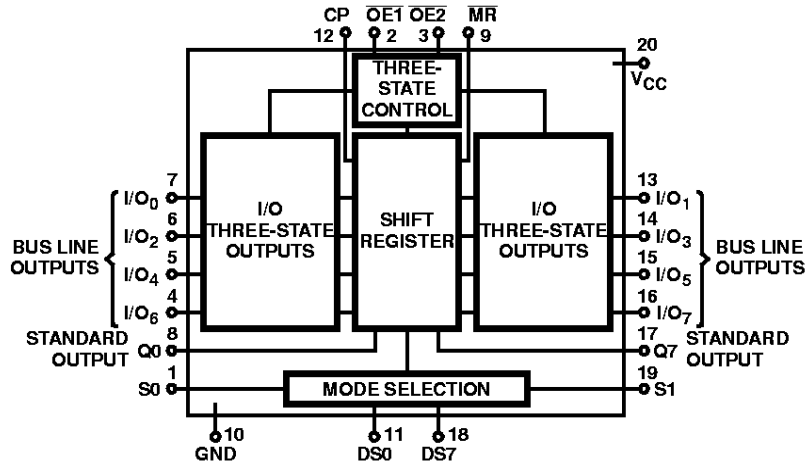
PART NUMBER	TEMP. RANGE (°C)	PACKAGE	PKG. NO.
CD74HC299E	-55 to 125	20 Ld PDIP	E20.3
CD74HCT299E	-55 to 125	20 Ld PDIP	E20.3
CD74HC299M	-55 to 125	20 Ld SOIC	M20.3
CD74HCT299M	-55 to 125	20 Ld SOIC	M20.3

#### NOTES:

1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
2. Wafer and die for this part number is available which meets all electrical specifications. Please contact your local sales office or Harris customer service for ordering information.

# CD74HC299, CD74HCT299

## Functional Diagram



**MODE SELECT FUNCTION TABLE THREE-STATE I/O PORT OPERATING MODE**

FUNCTION	INPUTS				INPUTS/OUTPUTS	
	OE1	OE2	S0	S1	Qn (REGISTER)	I/O0 --- I/O7
Read Register	L	L	L	X	L	L
	L	L	L	X	H	H
	L	L	X	L	L	L
	L	L	X	L	H	H
Load Register	X	X	H	H	Qn = I/On	I/On = Inputs
Disable I/O	H	X	X	X	X	(Z)
	X	H	X	X	X	(Z)

**TRUTH TABLE**

FUNCTION	INPUTS							REGISTER OUTPUTS				
	MR	CP	S0	S1	DS0	DS7	I/On	Q0	Q1	---	Q6	Q7
<b>RESET (CLEAR)</b>	L	X	X	X	X	X	X	L	L	---	L	L
Shift Right	H	↑	h	l	l	X	X	L	q0	---	q5	q6
	H	↑	h	l	h	X	X	H	q0	---	q5	Q6
Shift Left	H	↑	l	h	X	l	X	q1	q2	---	q7	L
	H	↑	l	h	X	h	X	q1	q2	---	q7	H
Hold (Do Nothing)	H	↑	l	l	X	X	X	q0	q1	---	q6	q7
Parallel Load	H	↑	h	h	X	X	l	L	L	---	L	L
	H	↑	h	h	X	X	h	H	H	---	H	H

NOTE: H = Input Voltage High Level, h = Input voltage high one set-up timer prior clock transition; L = Input Voltage Low Level; l = Input voltage low one set-up time prior clock transition; qn = Lower case letter indicates the state of the reference output one set-up time prior to clock transition; X - Voltage level on logic status don't care; Z = Output in high impedance state, ↑ = Low to High Clock Transition.

# CD74HC299, CD74HCT299

## Absolute Maximum Ratings

DC Supply Voltage, $V_{CC}$ .....	-0.5V to 7V
DC Input Diode Current, $I_{IK}$	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Output Diode Current, $I_{OK}$	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Drain Current, per Output, $I_O$ , For $-0.5V < V_O < V_{CC} + 0.5V$	
For Q Outputs .....	$\pm 25mA$
For I/O Outputs .....	$\pm 35mA$
DC Output Source or Sink Current per Output Pin, $I_O$	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ .....	$\pm 25mA$
DC $V_{CC}$ or Ground Current, $I_{CC}$ .....	$\pm 50mA$

## Thermal Information

Thermal Resistance (Typical, Note 3)	$\theta_{JA}$ ( $^{\circ}C/W$ )
PDIP Package .....	125
SOIC Package .....	120
Maximum Junction Temperature .....	150 $^{\circ}C$
Maximum Storage Temperature Range .....	-65 $^{\circ}C$ to 150 $^{\circ}C$
Maximum Lead Temperature (Soldering 10s) .....	300 $^{\circ}C$ (SOIC - Lead Tips Only)

## Operating Conditions

Temperature Range, $T_A$ .....	-55 $^{\circ}C$ to 125 $^{\circ}C$
Supply Voltage Range, $V_{CC}$	
HC Types .....	2V to 6V
HCT Types .....	4.5V to 5.5V
DC Input or Output Voltage, $V_I$ , $V_O$ .....	0V to $V_{CC}$
Input Rise and Fall Time	
2V .....	1000ns (Max)
4.5V .....	500ns (Max)
6V .....	400ns (Max)

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

**NOTE:**

- $\theta_{JA}$  is measured with the component mounted on an evaluation PC board in free air.

## DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		$V_{CC}$ (V)	25 $^{\circ}C$			-40 $^{\circ}C$ TO 85 $^{\circ}C$		-55 $^{\circ}C$ TO 125 $^{\circ}C$		UNITS		
		$V_I$ (V)	$I_O$ (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX			
<b>HC TYPES</b>														
High Level Input Voltage	$V_{IH}$	-	-	2	1.5	-	-	1.5	-	1.5	-	V		
				4.5	3.15	-	-	3.15	-	3.15	-	V		
				6	4.2	-	-	4.2	-	4.2	-	V		
Low Level Input Voltage	$V_{IL}$	-	-	2	-	-	0.5	-	0.5	-	0.5	V		
				4.5	-	-	1.35	-	1.35	-	1.35	V		
				6	-	-	1.8	-	1.8	-	1.8	V		
High Level Output Voltage CMOS Loads	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-0.02	2	1.9	-	-	1.9	-	1.9	-	V		
				4.5	4.4	-	-	4.4	-	4.4	-	V		
				6	5.9	-	-	5.9	-	5.9	-	V		
High Level Output Voltage TTL Loads	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-0.02	Qn	I/On	-	-	-	-	-	-	V		
				-4	-6	4.5	3.98	-	-	3.84	-	3.7	-	V
				-5.2	-7.8	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	$V_{OL}$	$V_{IH}$ or $V_{IL}$	0.02	2	-	-	0.1	-	0.1	-	0.1	V		
				4.5	-	-	0.1	-	0.1	-	0.1	V		
				6	-	-	0.1	-	0.1	-	0.1	V		
Low Level Output Voltage TTL Loads	$V_{OL}$	$V_{IH}$ or $V_{IL}$	0.02	Qn	I/On	-	-	-	-	-	-	V		
				4	6	4.5	-	-	0.26	-	0.33	-	0.4	V
				5.2	7.8	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	$I_I$	$V_{CC}$ or GND	-	6	-	-	$\pm 0.1$	-	$\pm 1$	-	$\pm 1$	$\mu A$		

## CD74HC299, CD74HCT299

### DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	6	-	-	8	-	80	-	160	μA
Three- State Leakage Current	V <sub>IL</sub> or V <sub>IH</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	-	6	-	-	±0.5	-	±5	-	±10	μA
<b>HCT TYPES</b>												
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> and GND	0	5.5	-	-	±0.1	-	±1	-	±1	μA
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	-	8	-	80	-	160	μA
Three- State Leakage Current	V <sub>IL</sub> or V <sub>IH</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	-	6	-	-	±0.5	-	±5	-	±10	μA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI <sub>CC</sub>	V <sub>CC</sub> -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μA

NOTE: For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4V, V<sub>CC</sub> = 5.5V) specification is 1.8mA.

### HCT Input Loading Table

INPUT	UNIT LOADS
S1, MR	0.25
I/O <sub>0</sub> - I/O <sub>7</sub>	0.25
DS0, DS7	0.25
S0, CP	0.6
OE1, OE2	0.3

NOTE: Unit load is ΔI<sub>CC</sub> limit specific in Static Specifications Table, e.g., 360μA max. at 25°C.

## CD74HC299, CD74HCT299

### Prerequisite for Switching Specifications

PARAMETER	SYMBOL	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
<b>HC TYPES</b>												
Maximum Clock Frequency	f <sub>MAX</sub>	2	6	-	-	5	-	-	4	-	-	MHz
		4.5	30	-	-	25	-	-	20	-	-	MHz
		6	35	-	-	29	-	-	23	-	-	MHz
MR Pulse Width	t <sub>w</sub>	2	50	-	-	65	-	-	75	-	-	ns
		4.5	10	-	-	13	-	-	15	-	-	ns
		6	9	-	-	11	-	-	13	-	-	ns
Clock Pulse Width	t <sub>w</sub>	2	80	-	-	100	-	-	120	-	-	ns
		4.5	16	-	-	20	-	-	24	-	-	ns
		6	14	-	-	17	-	-	20	-	-	ns
Setup Time DS0, DS7, I/On to Clock	t <sub>SU</sub>	2	100	-	-	125	-	-	150	-	-	ns
		4.5	20	-	-	25	-	-	30	-	-	ns
		6	17	-	-	21	-	-	26	-	-	ns
Hold Time DS0, DS7, I/On, S0, S1 to Clock	t <sub>H</sub>	2	0	-	-	0	-	-	0	-	-	ns
		4.5	0	-	-	0	-	-	0	-	-	ns
		6	0	-	-	0	-	-	0	-	-	ns
Recovery Time MR to Clock	t <sub>REC</sub>	2	5	-	-	5	-	-	5	-	-	ns
		4.5	5	-	-	5	-	-	5	-	-	ns
		6	5	-	-	5	-	-	5	-	-	ns
Setup Time S1, S0 to Clock	t <sub>SU</sub>	2	120	-	-	150	-	-	180	-	-	ns
		4.5	24	-	-	30	-	-	36	-	-	ns
		6	20	-	-	26	-	-	31	-	-	ns
<b>HCT TYPES</b>												
Maximum Clock Frequency	f <sub>MAX</sub>	4.5	25	-	-	20	-	-	16	-	-	ns
MR Pulse Width	t <sub>w</sub>	4.5	15	-	-	19	-	-	22	-	-	ns
Clock Pulse Width	t <sub>w</sub>	4.5	20	-	-	25	-	-	30	-	-	ns
Setup Time DS0, DS7, I/On, S0, S1 to Clock	t <sub>SU</sub>	4.5	20	-	-	25	-	-	30	-	-	ns
Hold Time DS0, DS7, I/On, S0, S1 to Clock	t <sub>H</sub>	4.5	0	-	-	0	-	-	0	-	-	ns
Recovery Time MR to Clock	t <sub>REC</sub>	4.5	5	-	-	5	-	-	5	-	-	ns
Setup Time S1, S0 to Clock	t <sub>SU</sub>	4.5	27	-	-	34	-	-	41	-	-	ns

## CD74HC299, CD74HCT299

**Switching Specifications**  $C_L = 50\text{pF}$ , Input  $t_r, t_f = 6\text{ns}$

PARAMETER	SYMBOL	TEST CONDITIONS	$V_{CC}$ (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>											
Propagation Delay Clock to I/O Output, Clock to Q0 and Q7, MR to Output	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	2	-	-	200	-	250	-	300	ns
			4.5	-	-	40	-	50	-	60	ns
		$C_L = 15\text{pF}$	5	-	17	-	-	-	-	-	ns
		$C_L = 50\text{pF}$	6	-	-	34	-	43	-	51	ns
Output Enable and Disable Times	$t_{PZL}$	$C_L = 15\text{pF}$	5	-	10	-	-	-	-	-	ns
	$t_{PZH}, t_{PLZ}$			-	13	-	-	-	-	-	ns
	$t_{PHZ}$			-	15	-	-	-	-	-	ns
Output High-Z to High Level	$t_{PZH}$	$C_L = 50\text{pF}$	2	-	-	155	-	195	-	235	ns
			4.5	-	-	31	-	39	-	47	ns
			6	-	-	26	-	33	-	40	ns
Output High Level to High-Z	$t_{PHZ}$	$C_L = 50\text{pF}$	2	-	-	185	-	230	-	280	ns
			4.5	-	-	37	-	46	-	56	ns
			6	-	-	31	-	39	-	48	ns
Output Low Level to High-Z	$t_{PLZ}$	$C_L = 50\text{pF}$	2	-	-	155	-	195	-	235	ns
			4.5	-	-	31	-	39	-	47	ns
			6	-	-	26	-	33	-	40	ns
Output High-Z to Low Level	$t_{PZL}$	$C_L = 50\text{pF}$	2	-	-	130	-	165	-	195	ns
			4.5	-	-	26	-	33	-	39	ns
			6	-	-	22	-	28	-	33	ns
Output Transition Time Q0, Q7	$t_{THL}, t_{TLH}$	$C_L = 50\text{pF}$	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
I/O <sub>0</sub> to I/O <sub>7</sub>	$t_{THL}, t_{TLH}$	$C_L = 50\text{pF}$	2	-	-	60	-	75	-	90	ns
			4.5	-	-	12	-	15	-	18	ns
			6	-	-	10	-	13	-	15	ns
Input Capacitance	$C_I$	$C_L = 50\text{pF}$	-	10	-	10	-	10	-	10	pF
Three-State Output Capacitance	$C_O$	-	-	20	-	20	-	20	-	20	pF
Power Dissipation Capacitance (Notes 4, 5)	$C_{PD}$	$C_L = 15\text{pF}$	5	-	150	-	-	-	-	-	pF

## CD74HC299, CD74HCT299

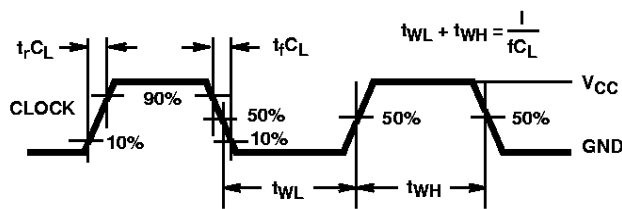
### Switching Specifications $C_L = 50\text{pF}$ , Input $t_r, t_f = 6\text{ns}$ (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	$V_{CC}$ (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HCT TYPES</b>											
Propagation Delay Clock to I/O Output, Clock to Q0 and Q7	$t_{PHL}, t_{PLH}$	$C_L = 50\text{pF}$	4.5	-	-	45	-	56	-	68	ns
		$C_L = 15\text{pF}$	5	-	19	-	-	-	-	-	ns
$\overline{MR}$ to Output	$t_{PHL}, t_{PLH}$	$C_L = 50\text{pF}$	4.5	-	-	46	-	58	-	69	ns
Output Enable and Disable Times	$t_{PZL}, t_{PZH}, t_{PLZ}, t_{PHZ}$	$C_L = 15\text{pF}$	5	-	10, 13, 15	-	-	-	-	-	ns
Output High-Z to High Level	$t_{PZH}$	$C_L = 50\text{pF}$	4.5	-	-	32	-	40	-	48	ns
Output High Level to High-Z	$t_{PHZ}$	$C_L = 50\text{pF}$	4.5	-	-	37	-	46	-	56	ns
Output Low Level to High-Z	$t_{PLZ}$	$C_L = 50\text{pF}$	4.5	-	-	32	-	40	-	48	ns
Output High-Z to Low Level	$t_{PZL}$	$C_L = 50\text{pF}$	4.5	-	-	30	-	38	-	45	ns
Output Transition Time Q0, Q7	$t_{TLH}, t_{THL}$	$C_L = 50\text{pF}$	4.5	-	-	15	-	19	-	22	ns
		$C_L = 50\text{pF}$	4.5	-	-	12	-	15	-	18	ns
I/O <sub>0</sub> to I/O <sub>7</sub>											
Input Capacitance	$C_{IN}$	$C_L = 50\text{pF}$	-	10	-	10	-	10	-	10	pF
Three-State Output Capacitance	$C_O$	-	-	20	-	20	-	20	-	20	pF
Power Dissipation Capacitance (Notes 4, 5)	$C_{PD}$	$C_L = 15\text{pF}$	5	-	170	-	-	-	-	-	pF

**NOTES:**

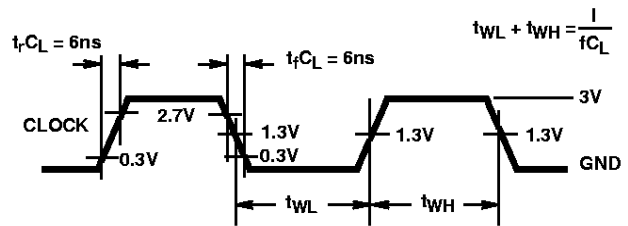
- $C_{PD}$  is used to determine the dynamic power consumption, per register.
- $P_D = C_{PD} V_{CC}^2 f_i + \sum (C_L V_{CC}^2 f_O)$  where  $f_i$  = Input Frequency,  $f_O$  = Output Frequency,  $C_L$  = Output Load Capacitance,  $V_{CC}$  = Supply Voltage.

### Test Circuits and Waveforms



NOTE: Outputs should be switching from 10%  $V_{CC}$  to 90%  $V_{CC}$  in accordance with device truth table. For  $f_{MAX}$ , input duty cycle = 50%.

**FIGURE 1. HC CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH**



NOTE: Outputs should be switching from 10%  $V_{CC}$  to 90%  $V_{CC}$  in accordance with device truth table. For  $f_{MAX}$ , input duty cycle = 50%.

**FIGURE 2. HCT CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH**

Test Circuits and Waveforms (Continued)

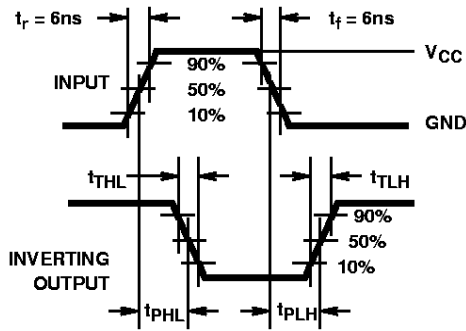


FIGURE 3. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

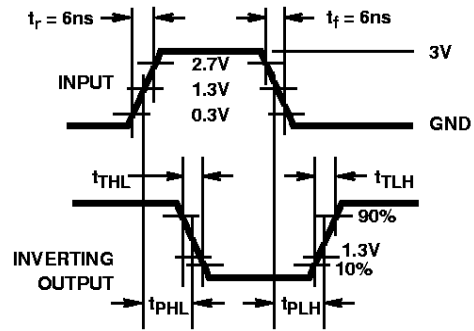


FIGURE 4. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

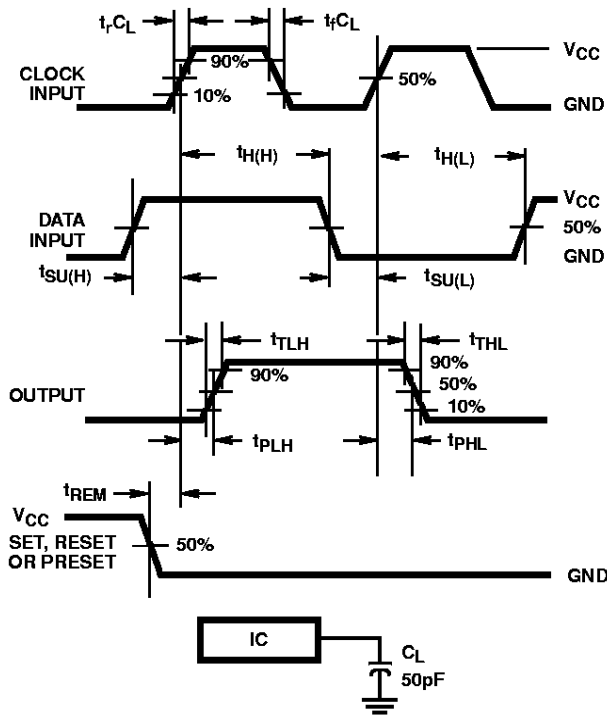


FIGURE 5. HC SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

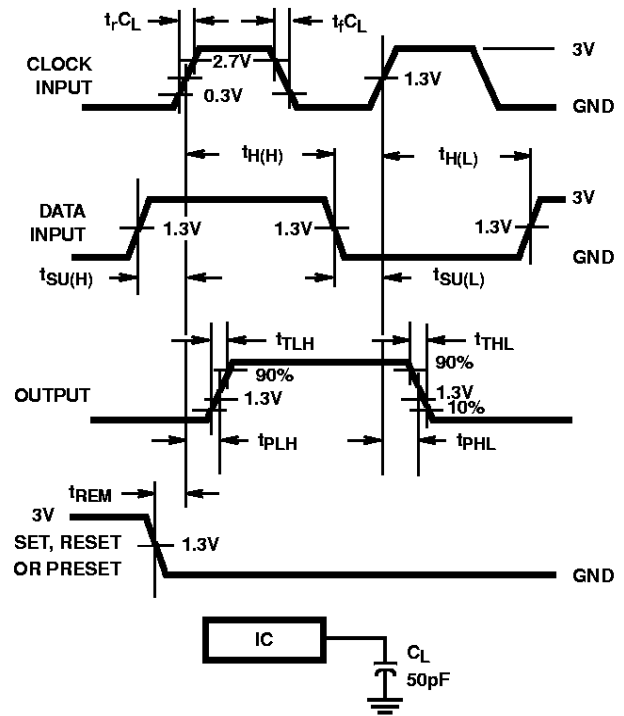


FIGURE 6. HCT SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS



**Test Circuits and Waveforms** (Continued)

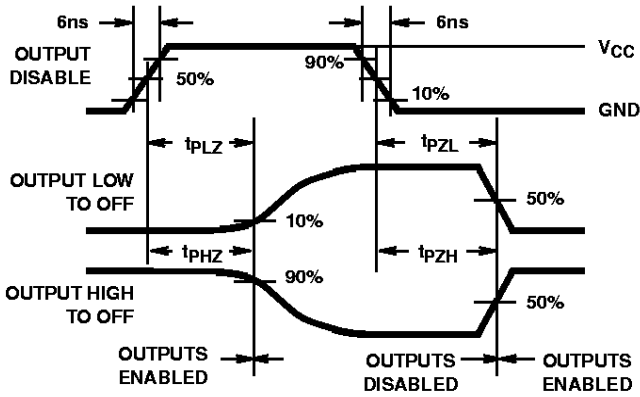


FIGURE 7. HC THREE-STATE PROPAGATION DELAY WAVEFORM

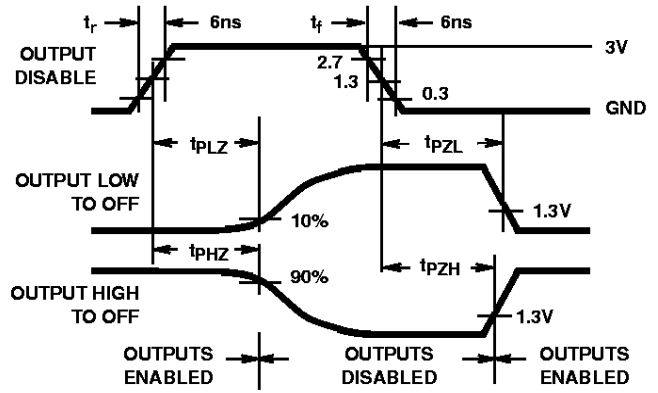
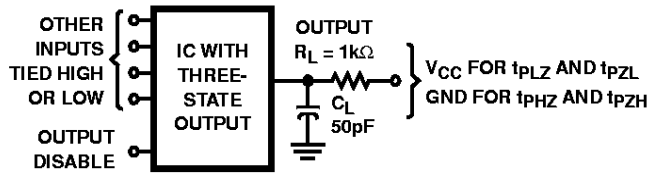


FIGURE 8. HCT THREE-STATE PROPAGATION DELAY WAVEFORM



NOTE: Open drain waveforms  $t_{pLZ}$  and  $t_{pZL}$  are the same as those for three-state shown on the left. The test circuit is Output  $R_L = 1k\Omega$  to  $V_{CC}$ ,  $C_L = 50pF$ .

FIGURE 9. HC AND HCT THREE-STATE PROPAGATION DELAY TEST CIRCUIT

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